

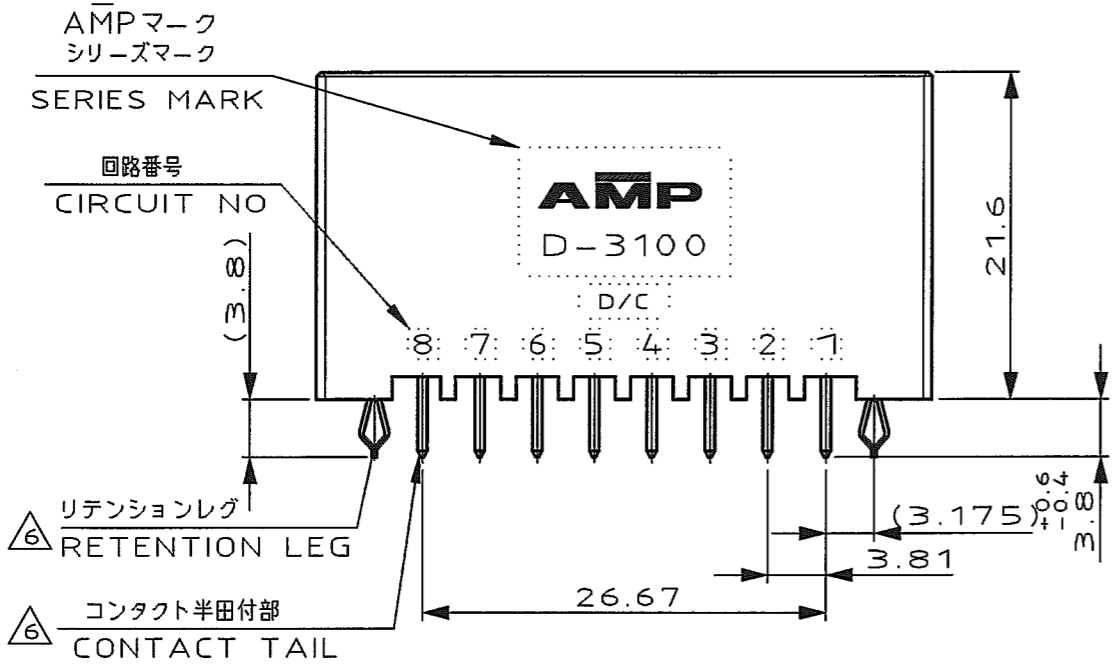
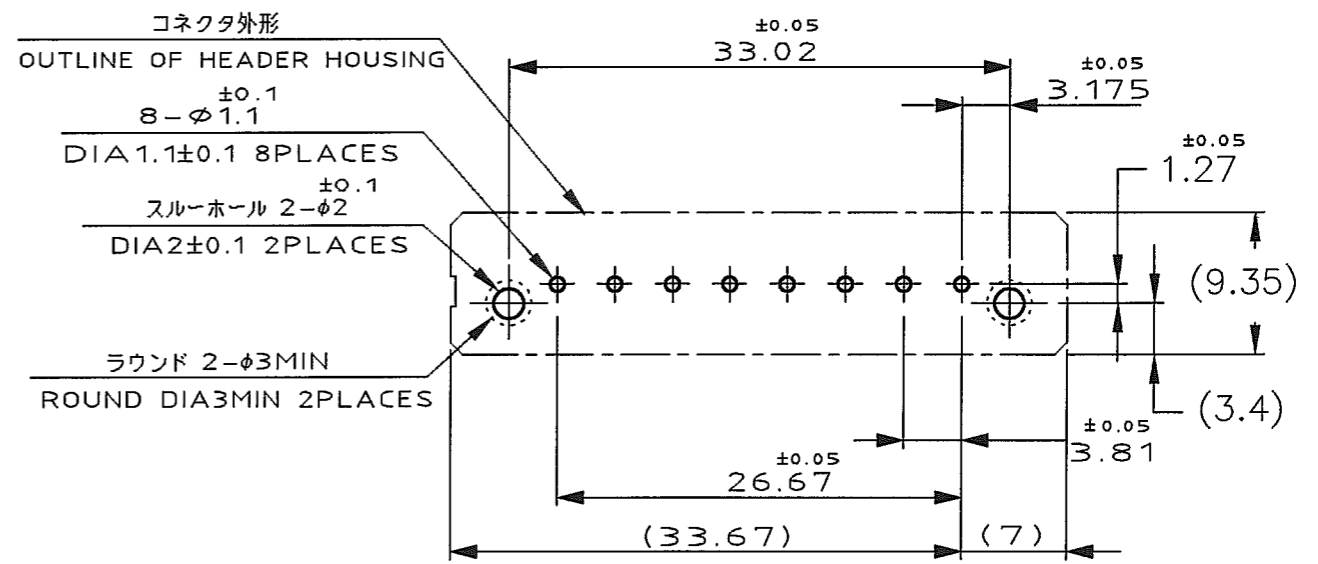
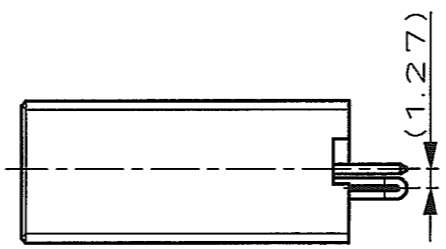
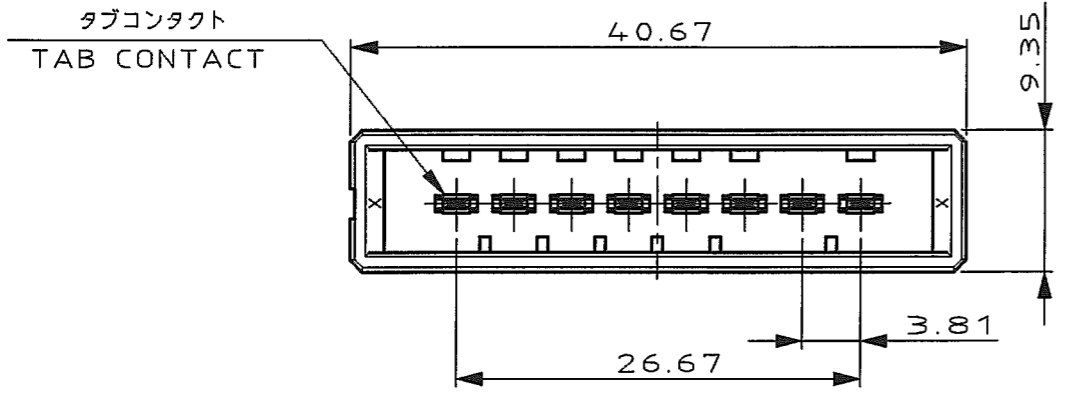
NUMBER 178317



METRIC

DIMENSIONS IN MILLIMETERS. DO NOT SCALE PRINT

PRINT DIST



推奨基板取付け寸法  
PC 基板厚: 1.6 ± 0.1  
(非累積公差)  
(コネクタ搭載面)

RECOMEND PC BOARD HOLE PATTERN  
PC BOARD THICKNESS: 1.6 ± 0.1  
(NOT ACCUMULATE TOLERANCE)  
(CONNECTOR MOUNT SIDE)

NOTES

1. MATERIAL: HOUSING: GLASS FILLED THERMO PLASTIC, POLYESTER (94V-0), COLOR: BLACK  
CONTACT: COPPER ALLOY  
RETENTION LEG: COPPER ALLOY
2. FINISH (CONTACT AREA): 0.38 μm MIN GOLD PLATING OVER Ni PLATING
3. FINISH (CONTACT AREA): 0.76 μm MIN GOLD PLATING OVER Ni PLATING
4. FINISH (CONTACT AREA): 2.0 μm MIN TIN PLATED OVER NICKEL
5. FINISH (RETENTION LEG): TIN-LEAD PLATED (CONTACT TAIL) OVER NICKEL
6. FINISH (RETENTION LEG): TIN PLATED (CONTACT TAIL) OVER NICKEL

注記

1. 材料: ハウジング: ガラス入り熱可塑性ポリエステル樹脂 (94V-0), 色: 黒  
コンタクト: 銅合金  
リテンションレグ: 銅合金
2. めっき: コンタクト: 全面Ni下地  
接触部: 0.38 μm MIN金めっき
3. めっき: コンタクト: 全面Ni下地  
接触部: 0.76 μm MIN金めっき
4. めっき: コンタクト: 全面Ni下地  
接触部: 2.0 μm MINスズめっき
5. めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上に半田めっき
6. めっき: リテンションレグとコンタクト半田付部  
ニッケル下地の上にスズめっき

6	4	1-178317-5
6	3	1-178317-3
6	2	1-178317-2
(FINISH)	製品番号 (PART NO.)	

REV	DESCRIPTION	DATE	BY	CHK	DATE
E	REVISED	FJD0-0039-03	T.S.M.	S.M.	6/2 '03
D	REVISED	FJD0-0114-03	T.S.M.	S.M.	25.APR '03
C	REVISED	FJ00-2744-95	KI.Y.I.	Y.I.	16/JUN '95
B	REVISED	FJ00-0838-94	NM	S.M.	7/4 '94
A	REDRAWN WITH CHANGE	FJ00-0480-94	NM	S.M.	4/20 '94

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**tyco Electronics** Tyco Electronics AMP K.K. Kawasaki, Japan

WIRE RANGE	INSULATION DIA	NAME
mm?(AWG - )	mmφ	8 POS SINGLE ROW VERTICAL HDR ASS'Y FOR DYNAMIC D-3100
MATERIAL	FINISH	一般公差 (GENERAL TOLERANCE)
SEE NOTE 注記参照	SEE NOTE 注記参照	10KF : ±0.3
DR. N. Matsubara	DE. N. Matsubara	100KF 30MF : ±0.4
19 APR 94	19 APR 94	300KF 100KF : ±0.45
CHK. S. MANABE	APP. S. MANABE	角 度 : ±3'
LTR	REVISION RECORD	DR
DR	CHK	DATE
SCALE	REV.	SHEET
2-1	E	1 OF 1